

DATASHEET

6 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER CNY17-X Series CNY17F-X Series







Features:

Current transfer ratios in selected narrow range groups
 CNN47.4 CNN47.5 4: 40.80%

CNY17-1, CNY17F-1: 40-80%

CNY17-2, CNY17F-2: 63-125%

CNY17-3, CNY17F-3: 100-200%

CNY17-4, CNY17F-4:160-320%

- High isolation voltage between input and output (Viso = 5000 Vrms)
- Creepage distance > 7.6 mm
- Operating temperature up to +110°C
- The CNY17F-X series offers no external base connection for minimum noise susceptibility
- Compact dual-in-line package
- •The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved

CQC approved

Schematic

6 B A 1 C 2 S C 2 NC 3 4 E NC 3

CNY17-X

Pin Configuration

- 1. Anode
- 2. Cathode
- 3. No Connection
- 4. Emitter
- 5. Collector
- 6. Base

Pin Configuration

CNY17F-X

Schematic

6 NC

5 C

- 1. Anode
- 2. Cathode
- 3. No Connection
- 4. Emitter
- 5. Collector
- 6. No Connection

Description

The CNY17-X and CNY17F-X series of devices each consist of an infrared emitting diode optically coupled to a phototransistor.

They are packaged in a 6-pin DIP package and available in wide-lead spacing and SMD option.

Applications

- · Power supply regulators
- Digital logic inputs
- Microprocessor inputs



Absolute Maximum Ratings (Ta=25℃)

	Parameter	Symbol	Rating	Unit
	Forward current	I _F	60	mA
	Peak forward current (t = 10µs)	I _{FM}	1	А
Input	Reverse voltage	V _R	6	V
	Power dissipation ($T_A = 25^{\circ}C$)	D	100	mW
	Derating factor (above 100°C)	P _D —	3.8	mW/°C
Output	Collector-Emitter voltage	$V_{\sf CEO}$	80	V
	Collector-Base voltage*1	V _{CBO}	80	V
	Emitter-Collector voltage	V _{ECO}	7	V
	Emitter-Base voltage	V _{EBO}	7	V
	Power dissipation (T _A = 25°C)	D	150	mW
	Derating factor (above 100°C)	P _C —	9.0	mW/°C
Total Power	Dissipation	P _{TOT}	200	mW
Isolation vol	tage *2	V _{ISO}	5000	V rms
Operating To	emperature	T _{OPR}	-55 to 110	°C
Storage Ten	nperature	T _{STG}	-55 to 125	°C
Soldering te	emperature *3	T _{SOL}	260	°C

Notes:

^{*1} Only for CNY17-X series.

^{*2} AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 & 3 are shorted together, and pins 4, 5 & 6 are shorted together.

^{*3} For 10 seconds.



Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward voltage	V_{F}	-	-	1.65	V	I _F = 60mA
Reverse current	I_R	-	-	10	μΑ	$V_R = 6V$
Input capacitance	C _{in}	-	18	-	pF	V = 0, f = 1MHz

Output

Parameter		Symbol	Min	Тур.	Max.	Unit	Condition
Collector-Base dark current	CNY17-X only	ГСВО	-	-	20	nA	V _{CB} = 10V, I _F = 0mA
Collector-Emitter da	ark current	I _{CEO}		-	50	nA	V _{CE} = 10V, IF=0mA
Collector-Emitter breakdown voltage		BV_CEO	80	-	-	V	$I_C = 1 \text{mA}, I_F = 0 \text{mA}$
Collector-Base breakdown voltage	CNY17-X only	BV_CBO	80	1:6		V	$I_C = 0.1 \text{mA},$ $I_F = 0 \text{mA}$
Emitter-Collector breakdown voltage		BV _{ECO}	7	11.0	-	V	$I_E = 0.1 \text{mA},$ $I_F = 0 \text{mA}$
Collector-Emitter ca	pacitance	C_CE	-	8	-	pF	VCE = 0V, f =1MHz

^{*} Typical values at T_a = 25°C



Transfer Characteristics

Pa	arameter	Symbol	Min	Тур.	Max.	Unit	Condition	
	CNY17-1 CNY17F-1	— - CTR -	40	-	80	- %		
Current Transfer	CNY17-2 CNY17F-2		63	-	125		$I_F = 10 \text{mA} , V_{CE} = 5 \text{V}$	
Ratio	CNY17-3 CNY17F-3		100	-	200			
	CNY17-4 CNY17F-4		160	-	320			
CNY17-1 CNY17F-1			13	-	-			
Current	CNY17-2 CNY17F-2	— CTR - — -	22	-	-	%	$I_F = 1 \text{mA}$, $V_{CE} = 5 \text{V}$	
Transfer Ratio	CNY17-3 CNY17F-3		34	-	-			
	CNY17-4 CNY17F-4		56	-	-			
Collector-Emitter saturation voltage		V _{CE(sat)}	-	-	0.3	V	I _F = 10mA , I _C = 2.5mA	
Isolation resistance		R _{IO}	10 ¹¹	-	-	Ω	V _{IO} = 500Vdc	
Input-output	t capacitance	C _{IO}	-	0.5	•	pF	V _{IO} = 0, f = 1MHz	
Turn-on time	е	T_{on}		10	12			
Turn-off time	е	T_{off}	39-1	9	12		$V_{CC} = 10V$,	
Rise time		Tr	7.1	6	10		I_C = 2mA, R_L = 100 Ω See Fig. 11	
Fall time		T _f	-	8	10	μs		
Rise time		T _r	-	2	10		$V_{CC} = 5V, I_F = 10mA,$	
Fall time		T _f	-	3	10		$R_L = 75\Omega$, See Fig. 11	

^{*} Typical values at T_a = 25°C



Typical Electro-Optical Characteristics Curves

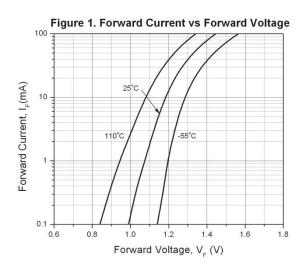


Figure 2. Current Tranfer Ratio vs Forward Current

1.2

0.6

0.7

1.0

0.7

1.0

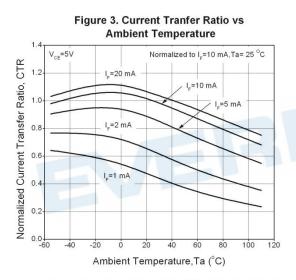
0.8

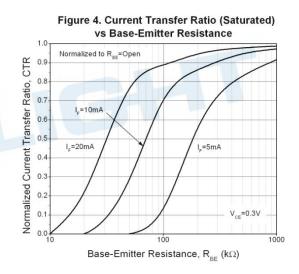
V_{cE}=5 V

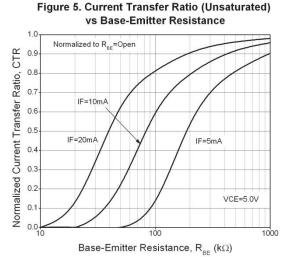
Ta=25°C

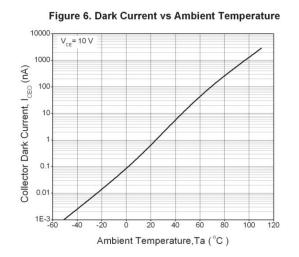
Normalized to I_F=10 mA

Forward Current, I_E (mA)









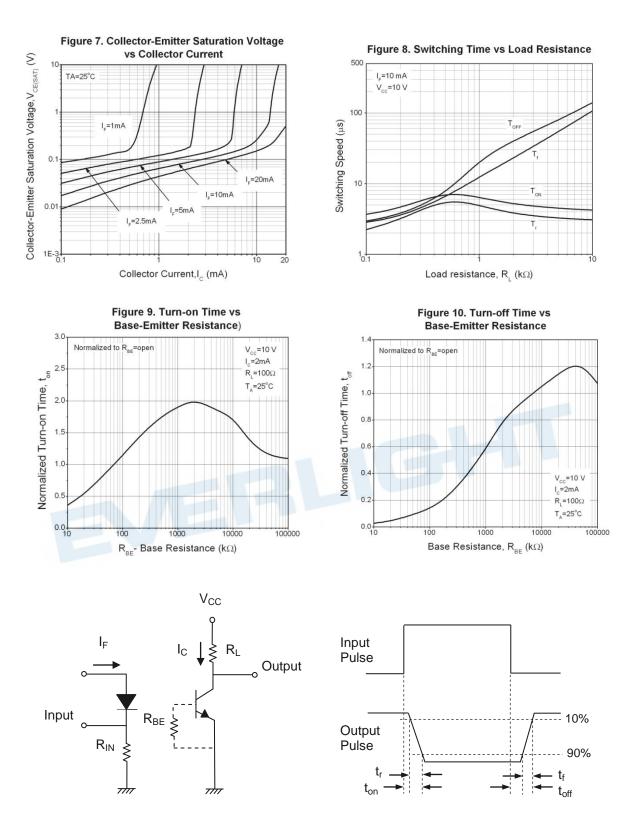


Figure 11. Switching Time Test Circuit & Waveforms



Order Information

Part Number

cny17-xy(z)-v cny17F-xy(z)-v

Note

X = Part no. (1, 2, 3 or 4)

Y = Lead form option (S, S1, M or none)

Z = Tape and reel option (TA, TB or none).

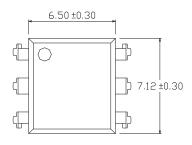
V = VDE (optional)

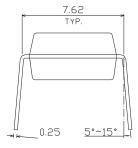
Option	Description	Packing quantity
None	Standard DIP-6	65 units per tube
М	Wide lead bend (0.4 inch spacing)	65 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

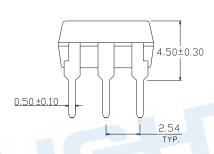


Package Dimension (Dimensions in mm)

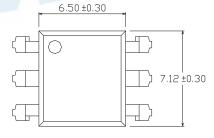
Standard DIP Type

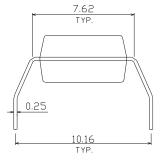


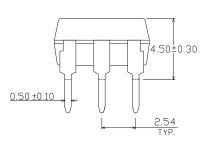




Option M Type

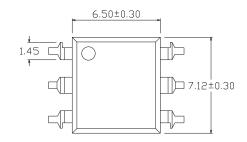


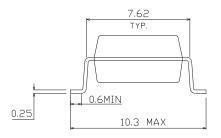


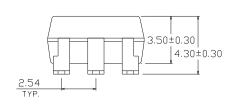




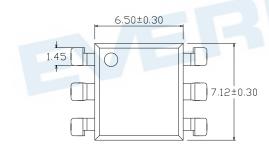
Option S Type

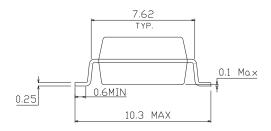


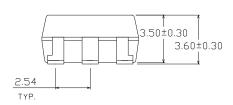




Option S1 Type

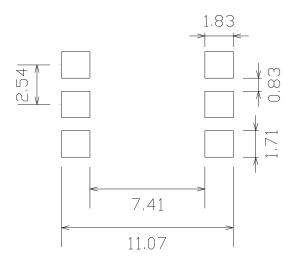








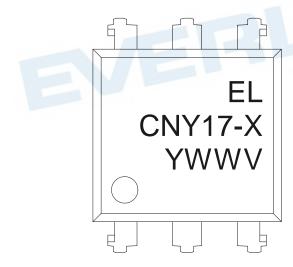
Recommended pad layout for surface mount leadform



Notes

Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Device Marking



Notes

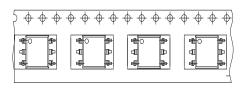
EL denotes Everlight

CNY17-X denotes Device Number (X: 1, 2, 3 or 4)

Y denotes 1 digit Year code WW denotes 2 digit Week code V denotes VDE (optional)

Tape & Reel Packing Specifications

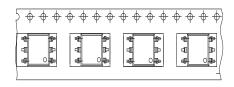
Option TA





Direction of feed from reel

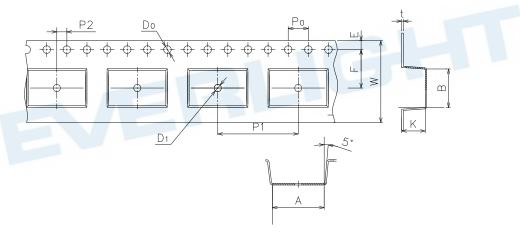
Option TB





Direction of feed from reel

Tape dimensions



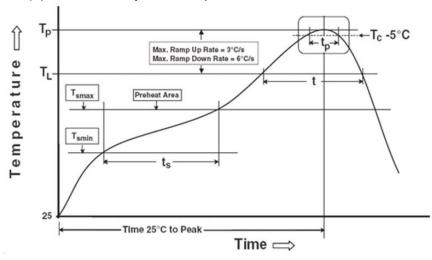
Dimension No.	A	В	Do	D1	E	F
Dimension (mm)	10.8±0.1	7.55±0.1	1.5±0.1	1.5+0.1/-0	1.75±0.1	7.5±0.1
Dimension No.			D0	_	147	.,
Dimension No.	Ро	P1	P2	t	W	K



Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Preheat

Temperature min (T_{smin}) 150 °C Temperature max (T_{smax}) 200°C

60-120 seconds Time $(T_{smin} \text{ to } T_{smax}) (t_s)$ Average ramp-up rate $(T_{smax} to T_p)$

Other

Liquidus Temperature (T_L)

Time above Liquidus Temperature (t L)

Peak Temperature (T_P)

Time within 5 °C of Actual Peak Temperature: T_P - 5°C

Ramp- Down Rate from Peak Temperature

Time 25°C to peak temperature

Reflow times

Reference: IPC/JEDEC J-STD-020D

3 °C/second max

217 °C

60-100 sec

260°C

30 s

6°C /second max.

8 minutes max.

3 times



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